



SiPM Fiber Tracker Cooling System Solutions

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Workshop on SiPM cooling for Fiber Tracker
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AGENDA

- Perfluorocarbon or not perfluorocarbon??
 - evaporative solution
 - mono-phase solution
- Details on the pre-study for SiPM cooling



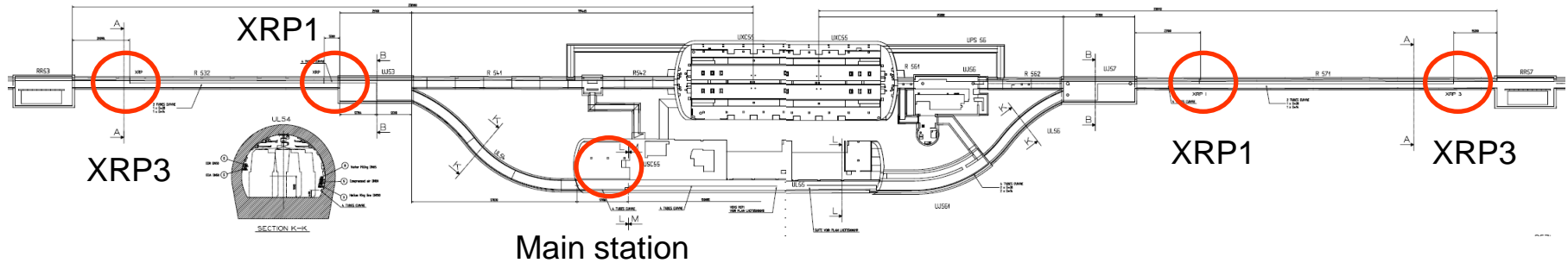


TOTEM Roman Pots

C_3F_8 Evaporative Cooling System

Eng Spec EDMS 778214 v1

POTS STATIONS LOCATION



DESIGN PARAMETERS

Coolant	C_3F_8
Expected heat load per single Pot	25 W
Design individual dissipation	50 W
Total design cooling capacity	1200 W
Maximum ΔT between sensors and fluid	10 °C
Silicon sensor operation temperature	-15 °C
Fluid evaporation temperature	-30 °C
Total design mass flow	40 g/s



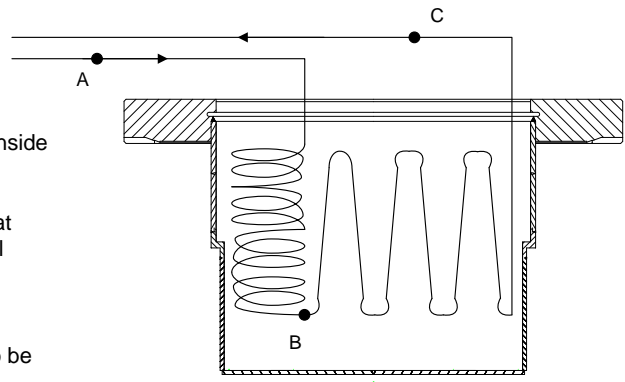
Roman Pot cooling Evaporative system @ C_3F_8

Lamination phase between points A and B

OPTION 1 - Capillary

lamination into a capillary located inside the Pot

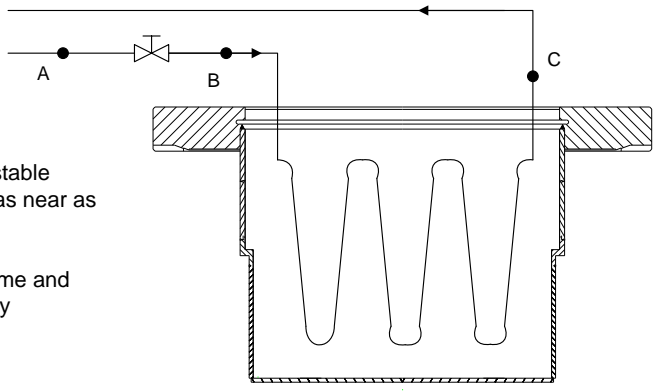
- + no need of insulation and heat intake on the supply line, horizontal flexibility
- to be individually tested, time consuming, behaviour off design to be studied



OPTION 2 - Manual valve

lamination into a manually adjustable valve located outside the Pots, as near as possible

- + commercial component, time and cost effective, reliability, flexibility
- need of insulation to avoid condensation, heat intake from environment



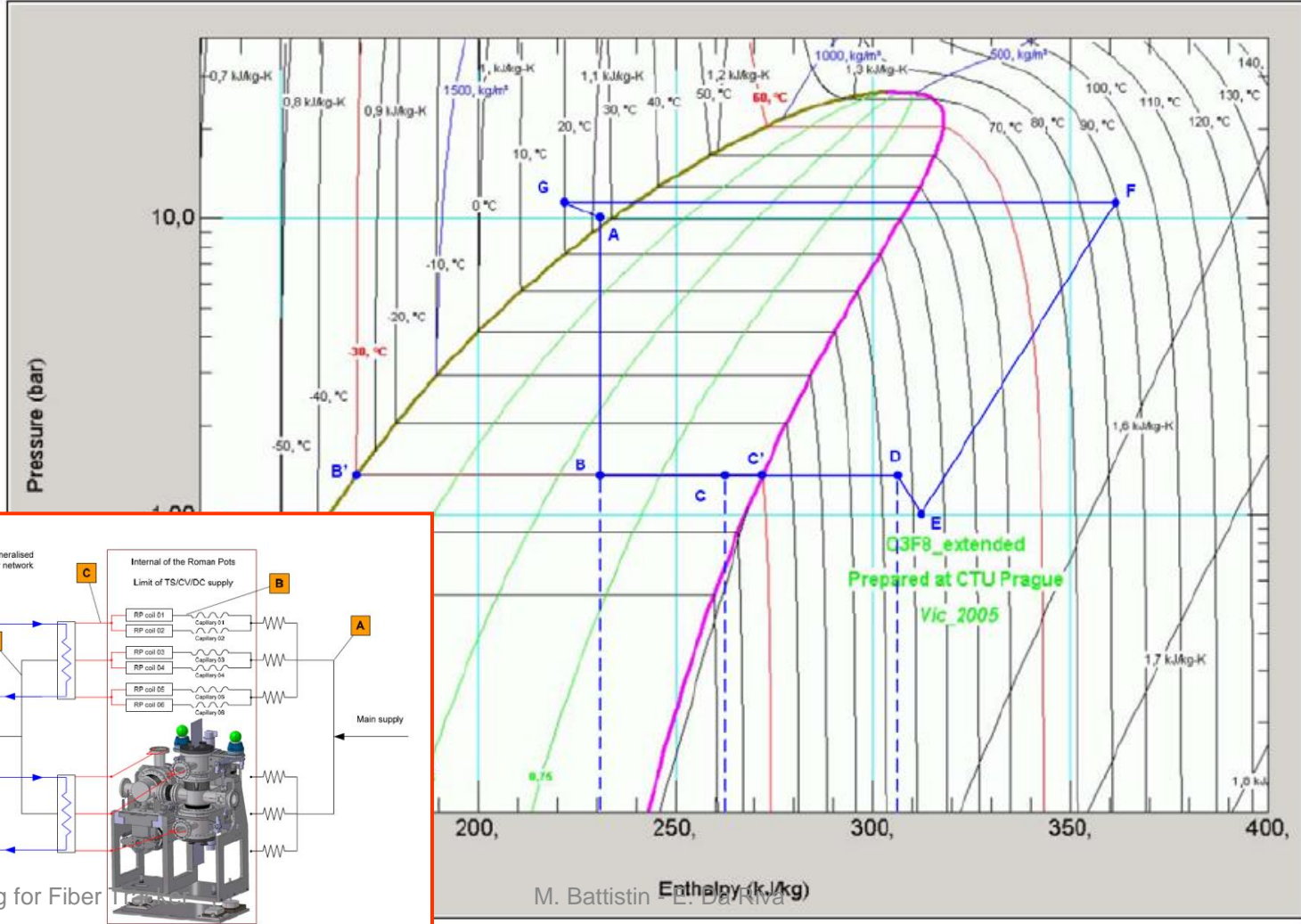
Compressor design
[data from HAUG, supplier of dry compressors successfully tested for SR1 and Atlas evaporative machine]

Nominal flow rate	2 g/s per circuit 48 g/s total 20.3 Nm³/h
Option 1	WTEGX 80/60 3 cylinders 2 stages 0.8-10 bara @ 13 Nm ³ /h 1.0-10 bara @ 18 Nm³/h ~30 kCHF
Option 2	VTOGX 120/60 2 cylinders 2 stages 0.8-10 bara @ 20 Nm ³ /h 1.0-10 bara @ 30 Nm ³ /h ~50 kCHF

2006 costs

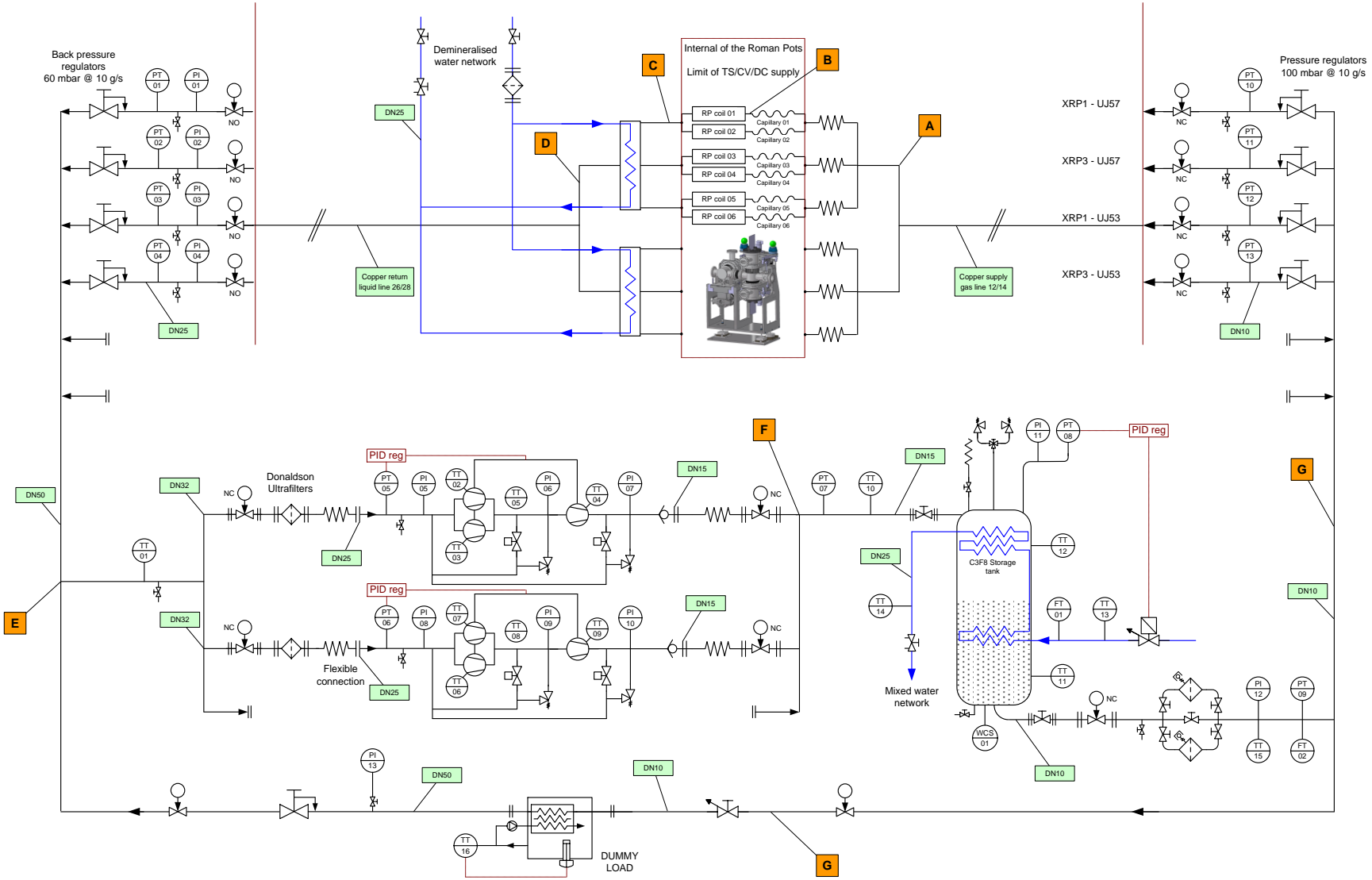


TOTEM RP cooling C_3F_8 main working points





TOTEM RP Cooling System Schematic



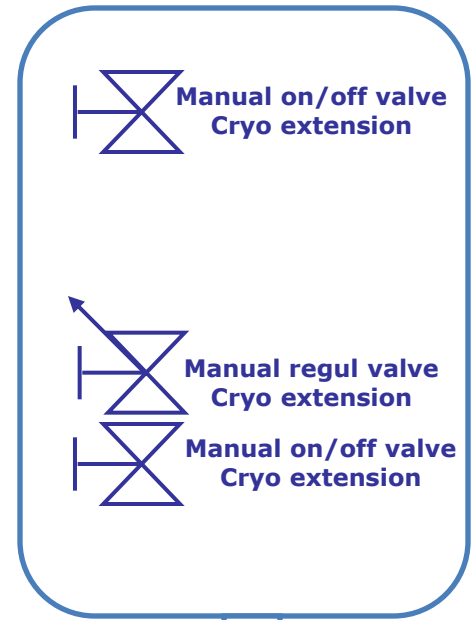
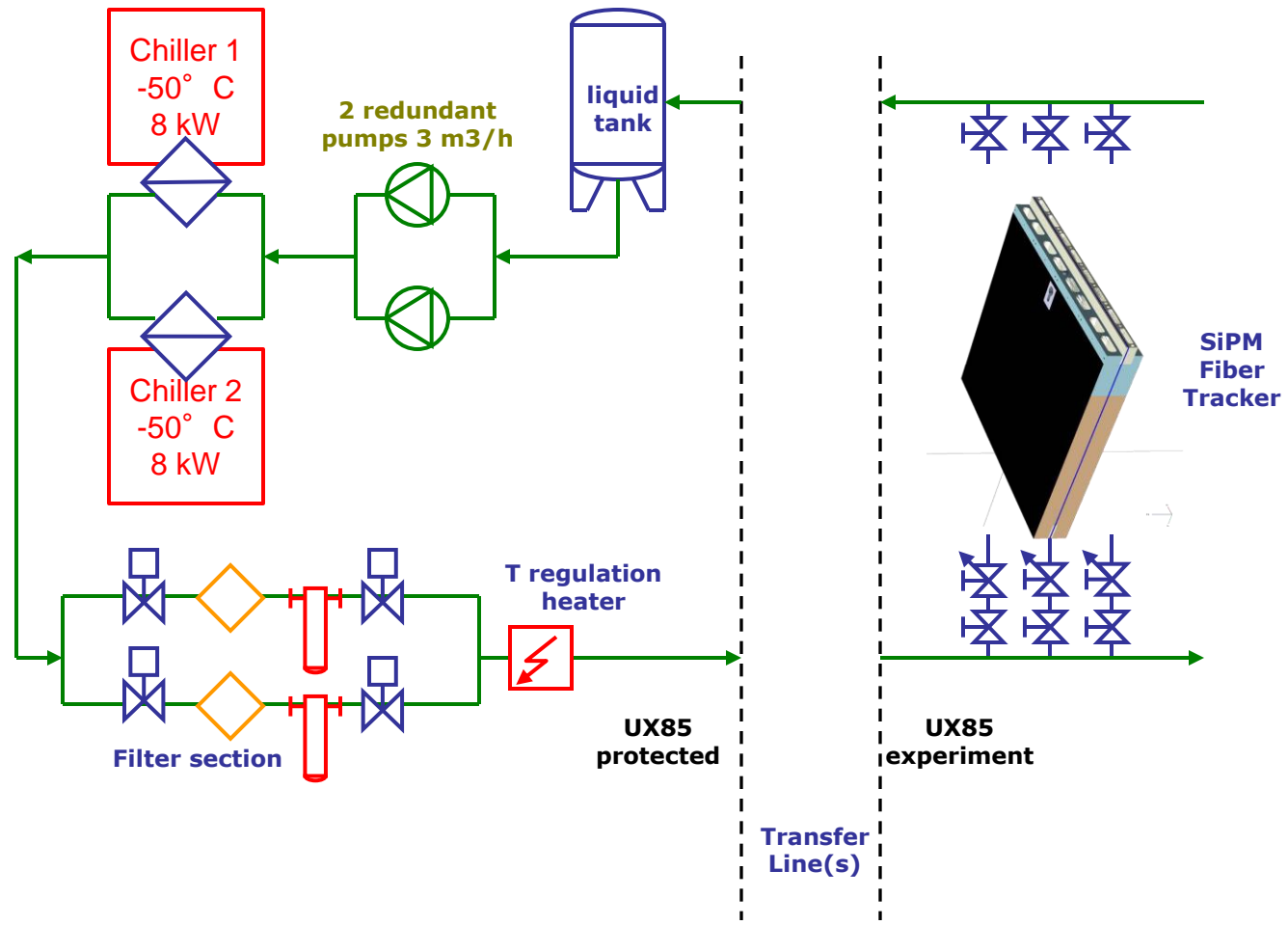


Could C_3F_8 or C_2F_6 Evaporative System Be the Solution for SiPM Fiber Tracker?

- The solution has already been used for TOTEM Roman Pots and ATLAS Blends
 - Low operation temperature easily achievable ($-43^{\circ}C$ during Totem tests with C_3F_8 – lower with C_2F_6);
 - Low operation pressure on the detector (0.8 - 1 bara);
 - Temperature stability and uniformity is granted by the evaporation pressure;
 - Transfer lines operate at ambient temperature: can be very long (300 m for Totem). The cooling station can be in an accessible area (no operation in the protected zone);
- Known technology both on detector structure than on the cooling system
 - The system is running since 2007 with high reliability;
- Cost estimate (based on TOTEM and ATLAS-Blends cooling):
 - Cooling station 250 kCHF @ 2007 (EN-CV-DC mechanical and electr. construction);
 - Copper not insulated transfer lines 30-50 kCHF;
 - Manifolding ??
- Do we need to use C_3F_8 ? **NO**
 - No radiation -> other industrial refrigerants (more green) could be studied (R23; R125;...)



A mono-phase system ??



For each distribution line
 -
 Large cost reduction possible
 reducing loops number



Could C_6F_{14} Mono-phase System Be the Solution for SiPM Fiber Tracker?

- The solution has already been used for 13 cooling systems for LHC Exp. detectors
 - LHCb Inner Tracker, Trigget Traker, Rich1&2;
 - Low operation temperature easily achivable (-50° C or less) depending on chiller selection;
 - Low opeartion pressure on the detector (3-5 bar);
 - Temperature stability and uniformity is granted by a fast T regulation heater;
 - Tranfer lines shall be insulated (0.5 K temperature rise – see: E. Da Riva);
- Known technology both on detector structure than on the cooling system
 - Refers to E. da Riva presentation this morning for the on-detector solution;
- Cost estimate (based on LHCb IT-TT-Rich cooling systems)
 - Cooling station: 140-180 kCHF @ 2013 (tendered);
 - Insulated transfer lines 80-100 kCHF;
 - Manifolding: about 1500 CHF/cooling loop (based on 48 loops of 6 modules – see E. Da Riva presentation);
- Do we need to use C_6F_{14} ? **NO**
 - No radiation -> other industrial (more green) fluids are available (NOVEC646 – see: E. Da Riva).



Conclusions

- Perfluorocarbons have no advantages: alternative fluids can be used in the same process installation.
- Liquid mono-phase cooling appears more appealing for
 - cooling system simplicity (installation & maintenance cost)
 - cooling efficiency (operation cost)
- Two-phases allows warm small pipe distribution up to the protected “enclave” (integration issues)

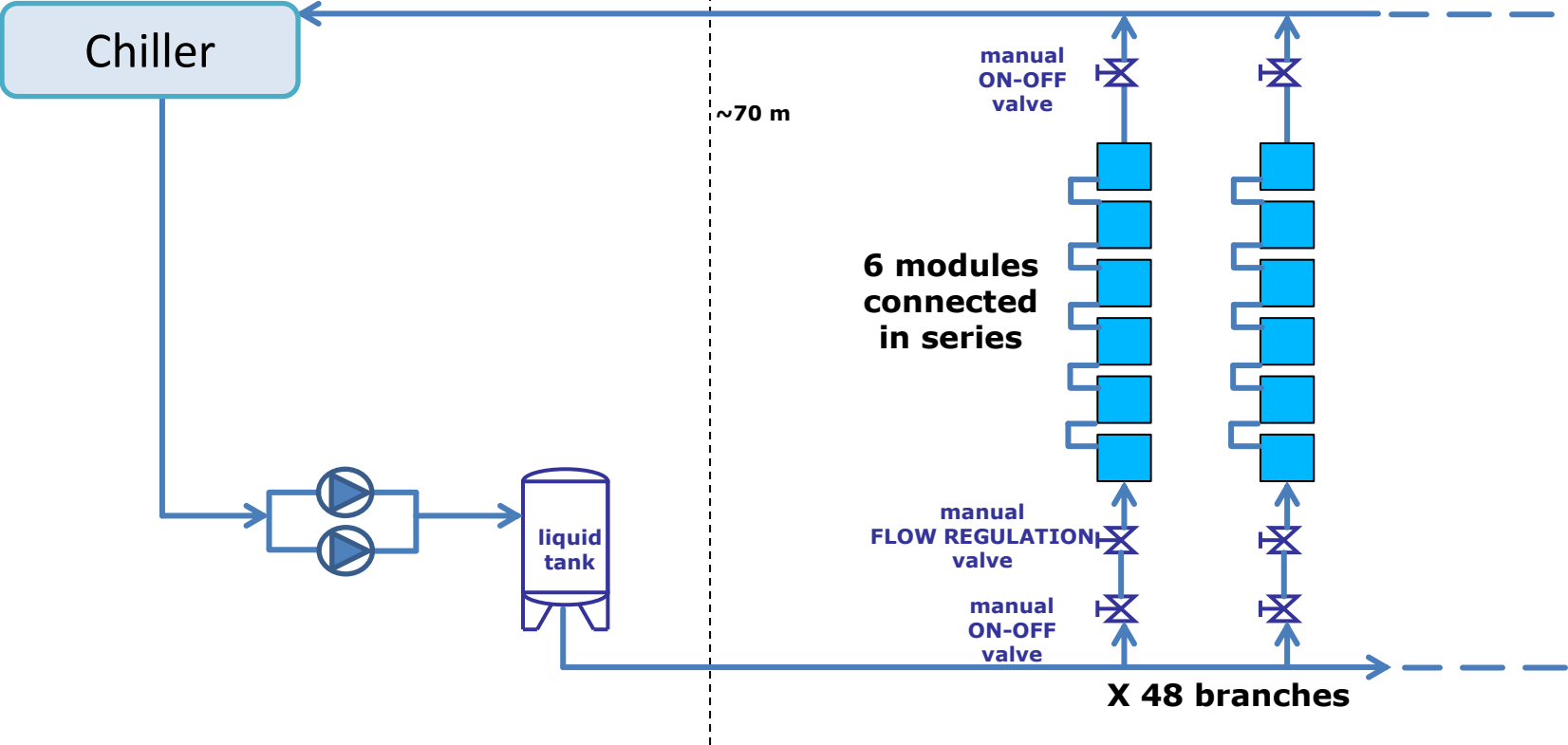




Thanks for your attention

You can find as back-up the details of the C_6F_{14} single-phase cooling system preliminary design done by Enrico Da Riva

“Order of magnitude estimate for open discussion”



- Very simple design, as compared to traditional two-phase systems, which would require 288 capillaries, automatic pressure regulation valve(s), (two-stage) compressor, lubricant-free compressor or dealing with oil return issues, higher system pressure ...;
- Only evident drawback: lines must be insulated, while two-phase system can have warm lines up to the capillaries and heater or water heat exchanger at the modules outlet;
- Temperature stability demanded to the chiller only, no other regulation needed (constant heat load);
- C_6F_{14} is not binding, “green” fluids such (e.g. its substitute NOVEC649) can be used, but tests needed.



MAIN COMPONENTS

- Chiller power: 5~8 kW @ -50° C (~5 kW from modules in the very worst case scenario assuming 20 W per module, ~3 kW due to heat pick-up along lines);
- Pump: 3.3 m³/h, $\Delta p \leq 3$ bar;
- Mass of C₆F₁₄: ~300 kg;
- 96 on/off valves (2 per branch);
- 48 manual flow regulation valves (1 per branch);
- Liquid tank / expansion vessel (~200 L);
- 336 connectors between modules;

MAIN DISTRIBUTION LINE

- DN32 (o.d. 42 mm), 1 m/s, 70 m + 70 m (a/r);
- 5 cm armaflex insulation, $T_{\text{surface}} \sim 17^{\circ}$ C, heat pick-up ~12 W/m;
- Temperature rise along 70 m: ~ 0.5 K;
- Δp along 70 m + 70 m ≤ 1 bar



MODULES LINES

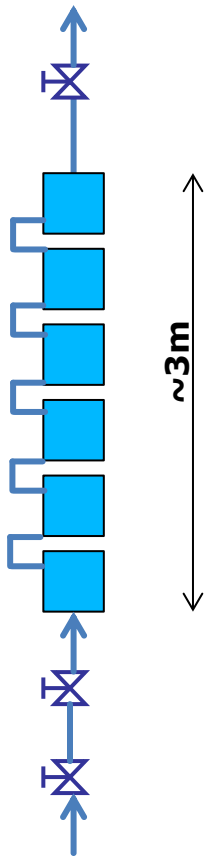
- 48 branches, 6 modules fed in series;
- i.d. 4 mm, o.d. 6 mm, 1.5 m/s;
- 3 cm armaflex insulation, $T_{\text{surface}} \sim 17^{\circ} \text{ C}$, heat pick-up $\sim 6 \text{ W/m}$;
- Refrigerant temperature rise along 5 m of insulated line: $< 1 \text{ K}$;
- Refrigerant temperature rise through 6 modules: 3.6 K [assuming 20 W per module];
- HTC: $1200 \text{ Wm}^{-2}\text{K}^{-1}$, refrigerant-to-wall ΔT : 2.6K [assuming 20 W per module];
- Δp through 6 modules (3 m + 24 bends) $\leq 1 \text{ bar}$.

EXPECTED SILICON DIE TEMPERATURE (worst case scenario)

- Assumption, ΔT through ceramic stiffener, flex-cable, teflon substrate $< 3\text{K}$;
- Silicon die at the beginning of the first module fed: -43.9° C ;
- Silicon die at the end of the last module fed: -40.3° C .



Serial vs parallel module connection



Serial connection is to be preferred to parallel connection:

- Much lower length to insulate → easier to install, lower heat load;
- Optimal flow rate in every module (good for HTC inside the pipes and heat pick up);
- Connectors can be installed between each module: in case of problems the two on/off valves can be closed, only 6 modules over 288 will be off, the faulty module alone can be removed.